



2020 INTERNATIONAL EOS/ESD SYMPOSIUM ON DESIGN AND SYSTEM (IEDS)

May 19-22, 2020

The Ritz-Carlton

Chengdu, China

CALL FOR PAPERS

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EOS/ESD Association, Inc.

EOS/ESD Association, Inc. is sponsoring the 2020 International EOS/ESD Symposium on Design and System (IEDS). IEDS 2020 is dedicated to the fundamental understanding of issues related to electrostatic discharge on design and system and the application of this knowledge to the solution of problems. The Technical Program Committee solicits symposium contributions, including data and analysis that advance the state-of-the-art knowledge, enhance or review the general knowledge, or discuss new topics related to on-chip ESD design, system ESD design and EOS/ESD issues in manufacturing. The Technical Program Committee is inviting papers related, but not limited, to the following tracks:

- ✓ Advanced CMOS EOS/ESD and Latch-up
- ✓ ESD protection in Bipolar, RF, High-voltage, and BCD technologies
- ✓ ESD modeling, simulation and design automation
- ✓ EOS/ESD Failure analysis and case studies
- ✓ ESD and latch-up testing
- ✓ System ESD design and troubleshooting issues
- ✓ ESD manufacturing control issues and target level discussion

Event Highlights: Awards are presented annually for the Symposium Outstanding Paper and Best Student Paper Award (selected by the Technical Program Committee). The Outstanding Paper is considered for presentation at the Annual EOS/ESD Symposium. Eligible student contributions for the Best Student Paper Award should be marked as such by the authors at the time of abstract submission.

IMPORTANT DATES

Oct. 14, 2019

Abstract Paper Submission Deadline

Nov. 20, 2019

Notification of Acceptance

Feb. 07, 2020

Author Registration/Final Paper
Submission Deadline

Submission Guidelines

Authors must submit a maximum 50-word abstract and 4-page maximum summary of their work. The summary must clearly state the purpose, results (e.g., data, diagrams, photographs, etc.), and conclusions of the work. Summaries must also include references to prior publications and state how the work enhances existing knowledge. Authors suggest the appropriate technical area related to their submission. Abstract submissions can be made electronically at:

<https://www.esda.org/events/abstract-submissions-for-ieds>